

## ABSTRACT

A semiconductor component includes a semiconductor die,  
5 and an on board capacitor on the die for filtering transient  
voltages, spurious signals and power supply noise in signals  
transmitted to the die. The capacitor includes a first  
electrode in electrical communication with a first terminal  
10 contact for the component, and a second electrode in  
electrical communication with a second terminal contact for  
the component. The electrodes are separated by a dielectric  
layer and protected by an outer protective layer of the  
component. The capacitor can be fabricated using  
redistribution layers on a wafer containing multiple dice.  
15 The component can be used to construct systems such as multi  
chip packages and multi chip modules.

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